

SN74ALVCH16901

18-BIT UNIVERSAL BUS TRANSCEIVER WITH PARITY GENERATORS/CHECKERS

SCES010F – JULY 1995 – REVISED SEPTEMBER 2004

- Member of the Texas Instruments Widebus™ Family
- UBT™ Transceiver Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, or Clocked Mode
- Operates From 1.65 V to 3.6 V
- Max t_{pd} of 4.4 ns at 3.3 V
- ± 24 -mA Output Drive at 3.3 V
- Simultaneously Generates and Checks Parity
- Option to Select Generate Parity and Check or Feed-Through Data/Parity in A-to-B or B-to-A Directions
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

description/ordering information

This 18-bit (dual-octal) noninverting registered transceiver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVCH16901 is a dual 9-bit to dual 9-bit parity transceiver with registers. The device can operate as a feed-through transceiver or it can generate/check parity from the two 8-bit data buses in either direction.

The SN74ALVCH16901 features independent clock (CLKAB or CLKBA), latch-enable (LEAB or LEBA), and dual 9-bit clock-enable ($\overline{\text{CLKENAB}}$ or $\overline{\text{CLKENBA}}$) inputs. It also provides parity-enable ($\overline{\text{SEL}}$) and parity-select (ODD/EVEN) inputs and separate error-signal ($\overline{\text{ERRA}}$ or $\overline{\text{ERRB}}$) outputs for checking parity. The direction of data flow is controlled by $\overline{\text{OEAB}}$ and $\overline{\text{OEBA}}$. When $\overline{\text{SEL}}$ is low, the parity functions are enabled. When $\overline{\text{SEL}}$ is high, the parity functions are disabled, and the device acts as an 18-bit registered transceiver.

DGG PACKAGE
(TOP VIEW)

1CLKENAB	1	64	1CLKENBA
LEAB	2	63	LEBA
CLKAB	3	62	CLKBA
1ERRA	4	61	1ERRB
1APAR	5	60	1BPAR
GND	6	59	GND
1A1	7	58	1B1
1A2	8	57	1B2
1A3	9	56	1B3
V _{CC}	10	55	V _{CC}
1A4	11	54	1B4
1A5	12	53	1B5
1A6	13	52	1B6
GND	14	51	GND
1A7	15	50	1B7
1A8	16	49	1B8
2A1	17	48	2B1
2A2	18	47	2B2
GND	19	46	GND
2A3	20	45	2B3
2A4	21	44	2B4
2A5	22	43	2B5
V _{CC}	23	42	V _{CC}
2A6	24	41	2B6
2A7	25	40	2B7
2A8	26	39	2B8
GND	27	38	GND
2APAR	28	37	2BPAR
2ERRA	29	36	2ERRB
OEAB	30	35	OEBA
SEL	31	34	ODD/EVEN
2CLKENAB	32	33	2CLKENBA

ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	TSSOP – DGG	Tape and reel	SN74ALVCH16901DGGR	ALVCH16901

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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description/ordering information (continued)

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The A and B I/Os and APAR and BPAR inputs have bus-hold circuitry. Active bus-hold circuitry holds unused or undriven data inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

Function Tables

FUNCTION [†]					
INPUTS					OUTPUT B
$\overline{CLKENAB}$	$\overline{OEAB}$	LEAB	CLKAB	A	
X	H	X	X	X	Z
X	L	H	X	L	L
X	L	H	X	H	H
H	L	L	X	X	$B_0^{\ddagger}$
L	L	L	$\uparrow$	L	L
L	L	L	$\uparrow$	H	H
L	L	L	L	X	$B_0^{\ddagger}$
L	L	L	H	X	$B_0^{\S}$

[†] A-to-B data flow is shown; B-to-A flow is similar, but uses $\overline{OEBA}$, LEBA, and $\overline{CLKENBA}$.

[‡] Output level before the indicated steady-state input conditions were established

[§] Output level before the indicated steady-state input conditions were established, provided that CLKAB was low before LEAB went low

INPUTS			OPERATION OR FUNCTION
$\overline{SEL}$	$\overline{OEBA}$	$\overline{OEAB}$	
L	H	L	Parity is checked on port A and is generated on port B.
L	L	H	Parity is checked on port B and is generated on port A.
L	H	H	Parity is checked on port B and port A.
L	L	L	Parity is generated on port A and B if device is in FF mode.
H	L	L	Parity functions are disabled; device acts as a standard 18-bit registered transceiver.
H	L	H	
H	H	L	
H	H	H	

Q_A data to B, Q_B data to A
 Q_B data to A
 Q_A data to B
 Isolation

Function Tables (Continued)

PARITY											
INPUTS								OUTPUTS			
$\overline{\text{SEL}}$	$\overline{\text{OEBA}}$	$\overline{\text{OEAB}}$	$\text{ODD}/\overline{\text{EVEN}}$	Σ OF INPUTS A1–A8 = H	Σ OF INPUTS B1–B8 = H	APAR	BPAR	APAR	$\overline{\text{ERRA}}$	BPAR	$\overline{\text{ERRB}}$
L	H	L	L	0, 2, 4, 6, 8	N/A	L	N/A	N/A	H	L	Z
L	H	L	L	1, 3, 5, 7	N/A	L	N/A	N/A	L	H	Z
L	H	L	L	0, 2, 4, 6, 8	N/A	H	N/A	N/A	L	L	Z
L	H	L	L	1, 3, 5, 7	N/A	H	N/A	N/A	H	H	Z
L	L	H	L	N/A	0, 2, 4, 6, 8	N/A	L	L	Z	N/A	H
L	L	H	L	N/A	1, 3, 5, 7	N/A	L	H	Z	N/A	L
L	L	H	L	N/A	0, 2, 4, 6, 8	N/A	H	L	Z	N/A	L
L	L	H	L	N/A	1, 3, 5, 7	N/A	H	H	Z	N/A	H
L	H	L	H	0, 2, 4, 6, 8	N/A	L	N/A	N/A	L	H	Z
L	H	L	H	1, 3, 5, 7	N/A	L	N/A	N/A	H	L	Z
L	H	L	H	0, 2, 4, 6, 8	N/A	H	N/A	N/A	H	H	Z
L	H	L	H	1, 3, 5, 7	N/A	H	N/A	N/A	L	L	Z
L	L	H	H	N/A	0, 2, 4, 6, 8	N/A	L	H	Z	N/A	L
L	L	H	H	N/A	1, 3, 5, 7	N/A	L	L	Z	N/A	H
L	L	H	H	N/A	0, 2, 4, 6, 8	N/A	H	H	Z	N/A	H
L	L	H	H	N/A	1, 3, 5, 7	N/A	H	H	L	Z	L
L	H	H	L	0, 2, 4, 6, 8	0, 2, 4, 6, 8	L	L	Z	H	Z	H
L	H	H	L	1, 3, 5, 7	1, 3, 5, 7	L	L	Z	L	Z	L
L	H	H	L	0, 2, 4, 6, 8	0, 2, 4, 6, 8	H	H	Z	L	Z	L
L	H	H	L	1, 3, 5, 7	1, 3, 5, 7	H	H	Z	H	Z	H
L	H	H	H	0, 2, 4, 6, 8	0, 2, 4, 6, 8	L	L	Z	L	Z	L
L	H	H	H	1, 3, 5, 7	1, 3, 5, 7	L	L	Z	H	Z	H
L	H	H	H	0, 2, 4, 6, 8	0, 2, 4, 6, 8	H	H	Z	H	Z	H
L	H	H	H	1, 3, 5, 7	1, 3, 5, 7	H	H	Z	L	Z	L
L	L	L	L	N/A	N/A	N/A	N/A	PE [†]	Z	PE [†]	Z
L	L	L	H	N/A	N/A	N/A	N/A	PO [‡]	Z	PO [‡]	Z

[†] Parity output is set to the level so that the specific bus side is set to even parity.

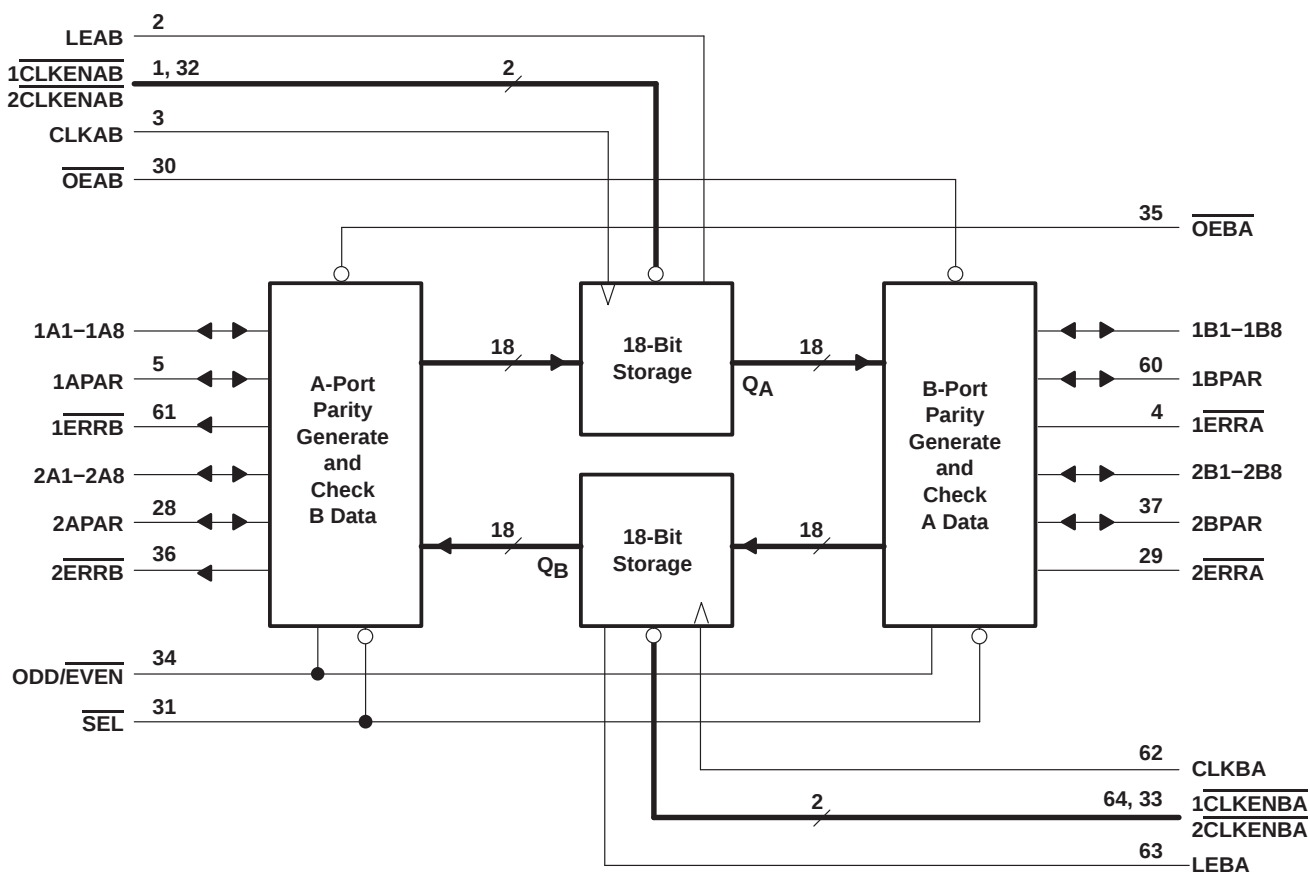
[‡] Parity output is set to the level so that the specific bus side is set to odd parity.

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functional block diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I : Except I/O ports (see Note 1)	–0.5 V to 4.6 V
I/O ports (see Notes 1 and 2)	–0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Notes 1 and 2)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Continuous output current, I_O	±50 mA
Continuous current through each V_{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 3)	55°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed..
2. This value is limited to 4.6 V maximum.
3. The package thermal impedance is calculated in accordance with JESD 51–7.

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recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V _{CC}	Supply voltage		1.65	3.6	V
V _{IH}	High-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	1.7		
		V _{CC} = 2.7 V to 3.6 V	2		
V _{IL}	Low-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.35 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	0.7		
		V _{CC} = 2.7 V to 3.6 V	0.8		
V _I	Input voltage		0	V _{CC}	V
V _O	Output voltage		0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 1.65 V	−4		mA
		V _{CC} = 2.3 V	−12		
		V _{CC} = 2.7 V	−12		
		V _{CC} = 3 V	−24		
I _{OL}	Low-level output current	V _{CC} = 1.65 V	4		mA
		V _{CC} = 2.3 V	12		
		V _{CC} = 2.7 V	12		
		V _{CC} = 3 V	24		
Δt/Δv	Input transition rise or fall rate		10		ns/V
T _A	Operating free-air temperature		−40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP [†]	MAX	UNIT
V _{OH}		I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} - 0.2			V
		I _{OH} = -4 mA	1.65 V	1.2			
		I _{OH} = -6 mA	2.3 V	2			
	I _{OH} = -12 mA		2.3 V	1.7			
			2.7 V	2.2			
			3 V	2.4			
		I _{OH} = -24 mA	3 V	2			
V _{OL}		I _{OL} = 100 μA	1.65 V to 3.6 V			0.2	V
		I _{OL} = 4 mA	1.65 V			0.45	
		I _{OL} = 6 mA	2.3 V			0.4	
	I _{OL} = 12 mA		2.3 V			0.7	
			2.7 V			0.4	
		I _{OL} = 24 mA	3 V			0.55	
I _I		V _I = V _{CC} or GND	3.6 V			±5	μA
I _I (hold)		V _I = 0.58 V	1.65 V	25			μA
		V _I = 1.07 V	1.65 V	-25			
		V _I = 0.7 V	2.3 V	45			
		V _I = 1.7 V	2.3 V	-45			
		V _I = 0.8 V	3 V	75			
		V _I = 2 V	3 V	-75			
		V _I = 0 to 3.6 V [‡]	3.6 V			±500	
I _{OZ} [§]		V _O = V _{CC} or GND	3.6 V			±10	μA
I _{CC}		V _I = V _{CC} or GND, I _O = 0	3.6 V			40	μA
ΔI _{CC}		One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V			750	μA
C _i	Control inputs	V _I = V _{CC} or GND	3.3 V	3			pF
C _{i0}	A or B ports	V _O = V _{CC} or GND	3.3 V	7.5			pF
C ₀	$\overline{\text{ERR}}$ ports	V _O = V _{CC} or GND	3.3 V	6			pF

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

[‡] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

[§] For I/O ports, the parameter I_{OZ} includes the input leakage current.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			V _{CC} = 1.8 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency		†		125		125		125		MHz
t _w	Pulse duration	CLK↑	†		3		3		3		ns
		LE high	†		3		3		3		
t _{su}	Setup time	A, APAR or B, BPAR before CLK↑	†		1.9		2		1.7		ns
		CLKEN before CLK↑	†		2.1		2.1		1.7		
		A, APAR or B, BPAR before LE↓	†		1.4		1.3		1.2		
t _h	Hold time	A, APAR or B, BPAR after CLK↑	†		0.4		0.4		0.5		ns
		CLKEN after CLK↑	†		0.5		0.5		0.7		
		A, APAR or B, BPAR after LE↓	†		0.9		1.1		0.9		

† This information was not available at the time of publication.

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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f _{max}			†		125		125		125		MHz
t _{pd}	A or B	B or A		†	1	5.2		4.8	1	4.4	ns
		BPAR or APAR		†	2	8.9		7.6	2	6.7	
	APAR or BPAR	BPAR or APAR		†	1	5.7		5.2	1	4.7	
		$\overline{\text{ERRA}}$ or $\overline{\text{ERRB}}$		†	2	9.7		8.7	2	7.5	
	ODD/ $\overline{\text{EVEN}}$	$\overline{\text{ERRA}}$ or $\overline{\text{ERRB}}$		†	1.5	8.7		7.9	1.5	6.8	
		BPAR or APAR		†	1.5	8.3		7.6	1.5	6.5	
	$\overline{\text{SEL}}$	BPAR or APAR		†	1	6.1		5.9	1	5.1	
	CLKAB or CLKBA	A or B		†	1	6.4		5.8	1	5.1	
		BPAR or APAR parity feed through		†	1.5	7.1		6.3	1.5	5.6	
		BPAR or APAR parity generated		†	2.5	10.2		8.7	2	7.7	
		$\overline{\text{ERRA}}$ or $\overline{\text{ERRB}}$		†	2.5	10.5		8.9	2	7.9	
	LEAB or LEBA	A or B		†	1	6		5.5	1	4.8	
		BPAR or APAR parity feed through		†	1.5	6.7		6	1.5	5.3	
		BPAR or APAR parity generated		†	2.5	9.8		8.3	2	7.4	
		$\overline{\text{ERRA}}$ or $\overline{\text{ERRB}}$		†	2.5	9.9		8.5	2	7.5	
t _{en}	$\overline{\text{OEAB}}$ or $\overline{\text{OEBA}}$	B, BPAR or A, APAR		†	1.4	6.3		6.1	1	5.3	ns
t _{dis}	$\overline{\text{OEAB}}$ or $\overline{\text{OEBA}}$	B, BPAR or A, APAR		†	1.3	6.1		5.2	1.5	4.9	ns
t _{en}	$\overline{\text{OEAB}}$ or $\overline{\text{OEBA}}$	$\overline{\text{ERRA}}$ or $\overline{\text{ERRB}}$		†	1.4	6.2		5.5	1	4.9	ns
t _{dis}	$\overline{\text{OEAB}}$ or $\overline{\text{OEBA}}$	$\overline{\text{ERRA}}$ or $\overline{\text{ERRB}}$		†	1.3	7.3		6.5	1	5.7	ns
t _{en}	$\overline{\text{SEL}}$	$\overline{\text{ERRA}}$ or $\overline{\text{ERRB}}$		†	1.4	6.7		6.5	1	5.5	ns
t _{dis}	$\overline{\text{SEL}}$	$\overline{\text{ERRA}}$ or $\overline{\text{ERRB}}$		†	1.3	6.4		5.4	1.5	4.9	ns

† This information was not available at the time of publication.

operating characteristics, T_A = 25°C

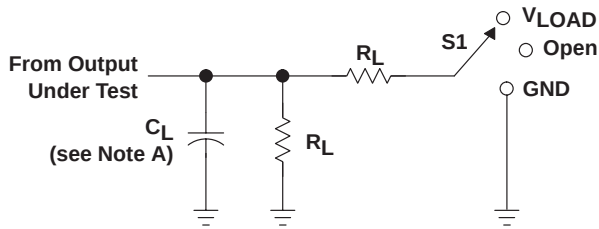
PARAMETER			TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	UNIT
				TYP	TYP	TYP	
C _{pd}	Power dissipation capacitance	Outputs enabled	C _L = 50 pF, f = 10 MHz	†	22	27	pF
		Outputs disabled		†	5	8	

† This information was not available at the time of publication.



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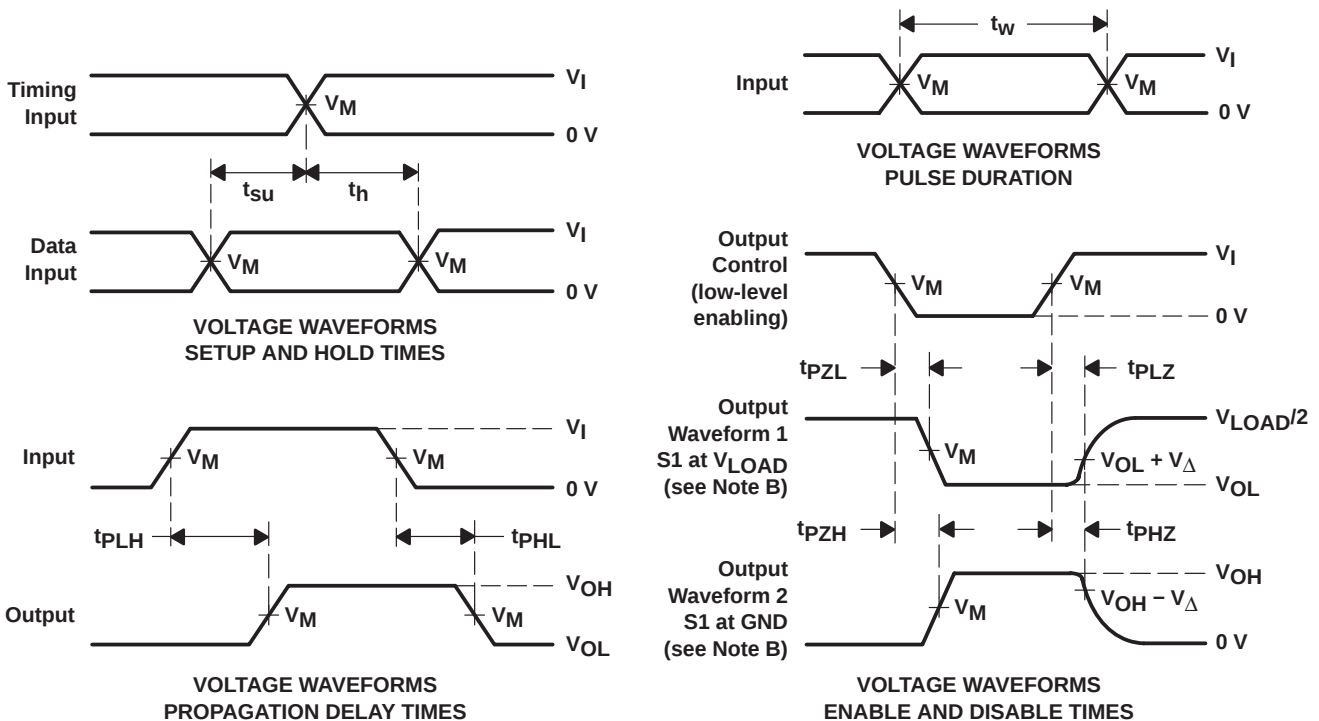
PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

TEST	S1
t_{pd} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open V_{LOAD} GND

V_{CC}	INPUT		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_r/t_f					
1.8 V	V_{CC}	≤ 2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5 \text{ V} \pm 0.2 \text{ V}$	V_{CC}	≤ 2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤ 2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
$3 \text{ V} \pm 0.3 \text{ V}$	2.7 V	≤ 2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .
 - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74ALVCH16901DGGR	Active	Production	TSSOP (DGG) 64	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16901
SN74ALVCH16901DGGR.B	Active	Production	TSSOP (DGG) 64	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16901

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVCH16901DGGR	TSSOP	DGG	64	2000	330.0	24.4	8.4	17.3	1.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVCH16901DGGR	TSSOP	DGG	64	2000	356.0	356.0	45.0

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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